Material Composition Declaration

This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard
http://www.ipc.org/IPC-175x

Form Type*
Distribute

Declaration Class*
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infomation

Supplier Information

Company Name * **Fairchild Semiconductor**	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	**Response Date*** **Sat, Aug 31, 2013 03:46 AM**
Contact Name * **David Lancaster**	Title - Contact Product Ecology	**Phone - Contact *** **801-562-7455**	**Email - Contact *** **david.lancaster@fairchildsemi.com**
Authorized Representative * **David Lancaster**	Title - Representative Product Ecology	**Phone - Representative *** **801-562-7455**	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	**Weight***	UOM	Unit Type
MOC217M	MOC217M	SO8-OPMOC(LFCu)			INTERNAL PENANG	**0.169000**	g	Each

Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Matte Tin (Sn)	CU Alloy	1	260 C	30 seconds	3

* Required Field

RoHS Material Composition Declaration	**Declaration Type * Custom**

RoHS Directive 2011/65/EU	**RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.

The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.

RoHS Declaration *	**1 - Item(s) does not contain RoHS restricted substances per the definition above**	**Supplier Acceptance * Accepted**

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2011/534/EU
None

Declaration Signature

Supplier Signature	David Lancaster DAVID LANCASTER - PRODUCT ECOLOGY MANAGER

Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name SO8-OPMOC(LFCu)

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	4.043	Supplier		Gallium Arsenide	0.283	1303-00-0	1675
			Supplier		Silicon	3.760	7440-21-3	22249
Coupling Gel	Other Organic Materials	4.596	Supplier		Dimethyl Cyclosiloxanes	0.046	69430-24-6	272
			Supplier		Methyltrimethoxysilane	0.460	1185-55-3	2722
			Supplier		Xylene	4.090	1330-20-7	24201
Die Attach	Other Organic Materials	0.754	Supplier		Acrylic Resin	0.151	54208-63-8	893
			Supplier		Silver	0.603	7440-22-4	3568
Encapsulation	Thermoplastics	98.060	B	Antimony/Antimony Compounds	Antimony Trioxide	2.940	1309-64-4	17396
			B	Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	3.920	6386-73-8	23195
			Supplier		Epoxy Resin	23.500	29690-82-2	139053
			Supplier		Silica, vitreous	67.700	60676-86-0	400592
Lead Frame	Copper & its alloys	59.197	Supplier		Copper	57.600	7440-50-8	340829
			Supplier		Iron	1.360	7439-89-6	8047
			Supplier		Phosphorus	0.018	7723-14-0	105
			Supplier		Silver	0.148	7440-22-4	876
			Supplier		Zinc	0.071	7440-66-6	420
Plating	Other Nonferrous metals & alloys	2.100	Supplier		Tin	2.100	7440-31-5	12426
Wire Bond	Precious metals	0.250	Supplier		Gold	0.250	7440-57-5	1479